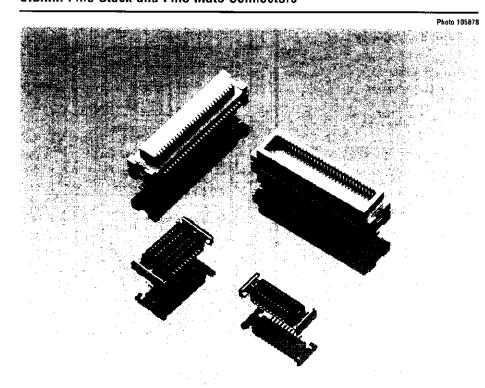


## 0.5mm Fine Stack and Fine Mate Connectors

## **Product Facts**

- Ultra fine, 0.5 (.020) pitch SMT connectors for boardto-board interconnections
- Low profile parallel board stacking heights as low as 1.5 [.059]
- Horizontal versions available for right-angle boardto-board applications
- Surface areas provided to accommodate vacuum nozzles
- Available packaged in tape and reel for automatic placement per EIAJ standards
- Offered with tin or gold plating on mating surfaces
- Solder pegs are included for anti-peeling



Note: Fine Stack connectors are shown at the bottom; Fine Mate connectors are shown on top.

The AMP 0.5mm Fine Stack and Fine Mate product lines are economical, surface-mount, ultra-fine pitch board-to-board connectors. Both product lines have been developed to meet the latest needs of the electronic industry for high density packaging.

These connectors offer a 0.5 [.020] contact pitch and paralle board stacking he ghts as low as 1.5 [.059] for Fine Stack connectors and ranging from 4.5 [.177] to 6.0 [.236] for Fine Mate connectors. They are ideally suited for applications requiring miniaturization, such as cellular phones, pagers, notebook computers, camcorders and other consumer electronics.

Both Fine Stack and Fine Mate connectors were designed for economical, automatic placement onto SMT printed circuit boards. The tabland receptacle designs include surface areas to accommodate "pick and place" vacuum nozzles without secondary covers. All products are "tape and reel" packaged, conforming to EIAJ stanidards.